

## **Product Information Sheet**

## **EPO-TEK® 314**

Minimum Alternative Cure(s):

180°C / 30 Minutes

120°C / 3 Hours

May not achieve performance properties listed below

Date: Recommended Cure: 150°C / 1 Hour July 2019

Rev:

Two

No. of Components: Mix Ratio by Weight: 100:6

Part A: 1.18 Part B: 1.23

Specific Gravity: Pot Life: 4 Days

Shelf Life- Syringe:

Shelf Life- Bulk: One year at room temperature Six months at -40°C

• Container(s) should be kept closed when not in use.

• Filled systems should be stirred thoroughly before mixing and prior to use.

• Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films

Product Description: A two component, high temperature grade, thermally and electrically insulating epoxy, designed for adhesive and sealing applications found in semiconductor, electro-optics, fiber optics, medical, and scientific/OEM industries. It is a low viscosity, optical grade epoxy with low index of refraction (Nd).

**Typical Properties:** Cure condition: 150°C / 1 Hour Different batches, conditions & applications yield differing results. Data below is not guaranteed. To be used as a guide only, not as a specification. \* denotes test on lot acceptance basis

PHYSICAL PROPERTIES:		
* Color (before cure):	Part A: Clear/co	olorless Part B: Amber
* Consistency:	Pourable liquid	
* Viscosity (23°C) @ 100 rpm:	300 - 600	cPs
Thixotropic Index:	N/A	
* Glass Transition Temp:	≥ 75	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Coefficient of Thermal Expansion (CTE	):	
Below T	g: 39	x 10 <sup>-6</sup> in/in°C
Above T	g: 134	x 10 <sup>-6</sup> in/in°C
Shore D Hardness:	83	
Lap Shear @ 23°C:	N/A	
Die Shear @ 23°C:	≥ 15	Kg 5,334 psi
Degradation Temp:	361	°C
Weight Loss:		
@ 200°	C: 0.18	%
@ 250°	C: 0.43	%
@ 300°	C: 1.03	%
Suggested Operating Temperature:	< 300	°C (Intermittent)
Storage Modulus:	275,210	psi
Particle Size:	N/A	

ELECTRICAL AND THERMAL PROPERTIES:				
Thermal Conductivity:	N/A			
Volume Resistivity @ 23°C:	$\geq 1 \times 10^{13}$	Ohm-cm		
Dielectric Constant (1KHz):	3.25			
Dissipation Factor (1KHz):	0.013			

<b>OPTICAL PROPERTIES @ 23°C:</b>		
Spectral Transmission:	> 96% @ 440-1680	nm
Refractive Index (uncured):	1.4965 @589	nm